






Layer	Calc Thickness	Primary Stack	Description
Layer - 1	0.0005 0.0018		Taiyo 4000-BN 1/2oz Sig (0.0012 Plt)
Layer - 2	0.0100 0.0012		R4350B 1oz P/G
Layer - 3	0.0058 0.0012		370H 1oz P/G
Layer - 4	0.0060 0.0012		370H 1oz P/G
Layer - 5	0.0058 0.0012		370H 1oz P/G
Layer - 6	0.0060 0.0012		370H 1oz P/G
Layer - 7	0.0058 0.0012		370H 1oz P/G
Layer - 8	0.0100 0.0018 0.0005		R4350B 1/2oz Sig (0.0012 Plt) Taiyo 4000-BN

Materials: Isola 370H High-Tg FR4
Rogers R4350B Thermoset/Ceramic

Requirement	Req. Thickness	Tol +	Tol -	Calc Thick
Incl. Plating & Mask	0.0620	0.0062	0.0062	0.0612
Incl. Mask over Laminate	0.0608	0.0061	0.0061	0.0576
Incl. Plating	0.0610	0.0061	0.0061	0.0602
After Lamination	0.0610	0.0031	0.0031	0.0578
Over Laminate	0.0598	0.0060	0.0060	0.0566

Impedance Type	Layer	Design	Actual	Pitch	Plane	Target	Tol (ohms)	Predict
1 Surface MS	L1	0.01950	0.0200	-	-	50	5.0	50.00
	-	-	-	-	L2			
2 Surface MS	L1	-	0.00875	-	-	75	7.5	74.51
	-	-	-	-	L2			
3 EC Microstrip	L1	0.00850	0.0095	0.0150	-	100	10.0	99.77
	-	0.00850	0.0095	-	L2			
4 EC Microstrip	L1	-	0.0042	0.0140	-	150	15.0	148.53
	-	-	0.0042	-	L2			
5 Surface MS	L8	0.01950	0.0200	-	L7	50	5.0	50.00
	-	-	-	-	-			

Impedance Type	Layer	Design	Actual	Pitch	Plane	Target	Tol (ohms)	Predict
6  Surface MS	L8	-	0.00875	-	L7	75	7.5	74.51
	-	-	-	-	-			
7  EC Microstrip	L8	0.00850	0.0095	0.0150	L7	100	10.0	99.77
	-	0.00850	0.0095	-	-			
8  EC Microstrip	L8	-	0.0042	0.0140	L7	150	15.0	148.53
	-	-	0.0042	-	-			